

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1 1. (Currently amended): A semiconductor laser module having a
2 semiconductor laser element, a submount bonded to this semiconductor laser element with a
3 solder layer in-between and thereby mounted with it, and a base mounted with this submount
4 with another solder layer in-between, wherein:

5 T/W ≥ 0.15 holds, where W is a width of said submount in a direction orthogonal
6 to an optical axis of said semiconductor laser element and T is a thickness of said submount, and
7 the main constituent material of said semiconductor laser element is indium-
8 phosphorus, the member constituting said submount is aluminum nitride, and the main
9 constituent material of said base is copper-tungsten.

2-6. (Canceled)